

DEVELOP NANOCOMPOSITE MATERIAL of $\text{TiO}_2/\text{Al}_2\text{O}_3$ USING
ELECTROPHORETIC DEPOSITION

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This work is dedicated to my beloved ,
father , mother ,brothers and sisters

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ABSTRACT

The methods have been developed for the manufacture of electrochemical deposition of coatings nanocomposite . Methods based on the electrophoretic deposition of nanoparticles . The method was developed for the deposition of EPD TiO_2 nanostructured films Al_2O_3 use of new agents to disperse . Copper has good corrosion resistance at room temperature , excellent malleability reproduction and susceptibility and electrical connections and high thermal , and apart from this it is cheap and abundantly available other metals from metals such as silver good measure . But poor mechanical properties such as hardness and wear resistance . Some applications , such as telecommunications switches require improvements in mechanical properties without losing a lot of heat and electrical connections . I have tried most of the modification alloying , but restrictions have been reported in alloying and reduce the negative in the thermal and electrical connections to it. Another way to improve the mechanical properties are modified with the surface through the development of composite coating on its surface .. has developed a coating with 10 g / l , and 30 g / l and 0 g / l concentrations that are not supported in the bath , in four different current densities (5 A/dm²) with the use of copper sulfate bath in order to study the effect of current density and the concentration of particles in the bath , on the structure and properties of advanced coating . The average crystal size in 64 -71 nm , and was obtained (220) strong texture in the paint and coatings copper compound is backed by identifying data XRD. Has been studied morphology and composition of the paint surface using SEM. Been determined hardness and wear resistance of coatings using micro- hardness testing and the ball on the plate wear test , and improve the hardness and wear resistance of the composite coatings were observed compared with copper paint is supported.

ABSTRAK

Kaedah-kaedah telah dibangunkan untuk pembuatan pemendapan elektrokimia penyalutan nanocomposite. Kaedah melibatkan pemendapan elektroforetik nanopartikel. Kaedah ini telah dibangunkan untuk pemendapan EPD TiO_2 filem bernanostruktur penggunaan Al_2O_3 ejen baru untuk bersurai. Tembaga mempunyai ketahanan kakisan yang baik pada suhu bilik, pembiakan sifat lunak yang sangat baik dan kecenderungan dan sambungan elektrik dan haba yang tinggi, dan selain daripada ini adalah murah dan banyak terdapat logam lain daripada logam seperti perak langkah yang baik. Tetapi sifat-sifat mekanikal miskin seperti kekerasan dan rintangan haus. Sesetengah aplikasi, seperti suis telekomunikasi memerlukan peningkatan dalam sifat mekanik tanpa kehilangan banyak haba dan sambungan elektrik. Saya telah mencuba kebanyakan pengaloi pengubahsuaian, tetapi sekatan telah dilaporkan di pengaloi dan mengurangkan negatif dalam sambungan haba dan elektrik kepadanya. Satu lagi cara untuk meningkatkan sifat-sifat mekanikal diubah suai dengan permukaan melalui pembangunan salutan komposit di permukaannya .. telah membangunkan salutan dengan 10 g / l, dan 30 g / l dan 0 g / l kepekatan yang tidak disokong dalam mandi, dalam empat berbeza densiti semasa (5 A/dm^2) dengan menggunakan mandi tembaga sulfat untuk mengkaji kesan ketumpatan arus dan kepekatan zarah di dalam bilik mandi, kepada struktur dan sifat-sifat lapisan maju. Saiz kristal purata dalam 64 -71 nm, dan telah diperolehi (220) tekstur kukuh dalam cat dan salutan sebatian tembaga disokong dengan mengenal pasti XRD data. Telah dikaji morfologi dan komposisi permukaan cat menggunakan SEM. Telah ditentukan kekerasan dan rintangan haus salutan menggunakan ujian mikro kekerasan dan bola pada ujian plat memakai, dan meningkatkan kekerasan dan memakai rintangan salutan komposit diperhatikan berbanding dengan cat tembaga disokong.

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CHAPTER 1

INTRODUCTION

1.1 Background

The field of nanocomposite materials has attracted attention of of scientists and engineers in recent years. Nanomaterials have attracted more and more compound of interest for the purpose of creation , which is expected to provide many of the advanced features of high-performance or high- functional materials . And the Compositecarries very different characteristics of the original components . And therefore , can not be of material which was built to be a multi-functional (Zhitomirsky, 2006).

The Composite is one of the most important categories of engineered materials , they provide many of the distinct characteristics compared with conventional materials . I have found this material applications increasingly wider in the general areas of chemistry, and physics , nanotechnology and materials science

and engineering. Copper (Cu) is an environment -friendly materials and abundantly available, which has a unique combination of low electrical resistivity ($16.78 \times 10^{-9} \Omega m$) and high thermal conductivity (394 WM-1K^{-1}), excellent malleability portability, attractive colors, reasonable resistance good corrosion at room temperature and recycling, and apart from this it is cheaper than other metals action (See, 1995).

Because of these characteristics of an excellent range of copper and its alloys are the most widely used and widely engineering materials for electrical conductivity (electrical connectors, wiring, connections, and plugs) and heat (heat exchangers, cushions, radiators, poles). However, poor mechanical property often requires promote without adversely affecting the electrical conduction convection her. Some applications, such as electrical contacts require surface good mechanical properties such as hardness basis, and corrosion resistance due to work rubbing repeatedly during the switch. Bulk modification alloying reduces the thermal and electrical conductivity, and along with the electrical conductivity, and thermal conductivity is also important so that communication can be called quickly accumulated heat due to the resistance heating and rubbing action during the switch. In such an approach surface engineering components is one of the wise because it does not adversely affect the bulk properties such as thermal and electrical connections, compared with wholesale amendment. A wide variety of surface coating techniques available are physical vapor deposition, chemical vapor deposition, thermal spraying, electrophoresis, deposition of electricity, and the spread of the paint, and the techniques that rely laser (laser cladding, etc.). nanocomposites and metal matrix containing dispersed particles of the second phase of our various special properties such as hardening of the dispersion, and self-lubricity, high temperature inertness, and good wear and corrosion resistance, and chemical and biological compatibility (Schnable, 1993).

Electrocodeposition has several advantages in the development of metal matrix composite coatings among other operations, such as deposits in the form of a unified complex substrates, and low cost, good reproducibility and reduce waste.

The Electrocodeposition process in use successfully for the development of such coatings nanocomposite of the past decades . Can be a hard second phase oxide (Al_2O_3 , TiO_2) (Gul , 2009) .

These applications include coatings wear and corrosion resistant surfaces , lubrication , tools high hardness , alloy and enhance dispersion , and protection against oxidation and hot corrosion (Saha , 2010) .

To work in parallel operation panel electrical current is used to improve the surface mechanical properties of copper without causing a negative It wiring harnesses and heat , by placing a layer of coating nanocomposite consists of a matrix of copper nanoparticle (TiO_2 , Al_2O_3) on the copper surface . And determine the optimum current density and the concentration of particles in the bath with the results achieved coating (Boccaccini, 2002).

Quality deposits are affected by a large number of variables that include current density , and the properties of the particles , and the formation of a bath, hydrodynamics and particle interaction bath . The amount of particles is an integral part of the second phase plays an important role in improving the mechanical properties of the surface by adjusting the grain size of the matrix , and also enhance the dispersion mechanism . Many of the parameters affecting the folder included . % Of second phase particles , including current density , and the particle concentration in the bath , and the pH of the solution are important variables . Current density plays an important role in the control of the deposition rate , which will in turn affect the concentration of particles included in the paint (Thiemig, 2008).

1.2 Objectives Of The Study

1. To synthesize nanocomposite TiO_2 and Al_2O_3 on copper substrate using electrophoretic deposition technique.
2. Investigation of deposition mechanism, and kinetics of deposition.
3. To determine the optimum concentration of composite $\text{TiO}_2/\text{Al}_2\text{O}_3$ on copper substrate.
4. To determine the characterizations of the coating substrate

1.3 Scope of the Work

Organizing the rest of the letter is as follows: for the preparation of nanocomposite $\text{TiO}_2 / \text{Al}_2\text{O}_3$ using the method of deposition Electrophoric. Mechanisms to promote different from copper , a brief explanation of the process of electrolysis with advantages over other coating techniques and applications and about codeposition electric , the impact of various factors on the characteristics of electrical codeposited coatings , and their applications , and review of the literature and a brief on the copper , and TiO_2 , Al_2O_3 provided paint compound in Chapter 2 . An experimental study has provided a detailed and different techniques on the descriptions in Chapter 3 . In Chapter 4, a discussion on the results that have been obtained from the descriptions of the powders (TiO_2 , Al_2O_3) along with the study of the mechanical property and provided samples of different co- deposited . In

Chapter 5 has been reported summary results and the main conclusions of this work .
The references provided in Chapter 6 .

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